Junction Diode - The semiconductor diode is formed by simply bringing n- and p-type materials together. Constructed from the same base - Ge orsi), as shown in the figure - At the instant the two materials are "joined" the electron and holes in the region of the junction will combine, resulting in a lack of carriers in the region near the junction. - This region of uncovered positive and negative ions is called the depletion region due to the depletion of carriers in this region. ninoning carrier flow Ie -Depletion region Majority corner flow. -Majority carrier + 0 + 0 + 00000majority carrier -Minonly carrier-ID= OMA VD= OV (nobias) & p-n junction with no external bias. - Since the diode is a two terminal device, the application of a voltage across its terminals leaves three possibilities. 1- no bias (40 = 0V) 2 - forward bias (VD) OV) 3- reverse bias (VD LOV)

No Bias (VD ZD)

- Under no-bias (no applied voltage) conditions, any minority carriers (holes) in n-type material that find themselves within the depletion region will pass directly into the p-type

- The closer the minority carrier is to the junction, the greater the attraction for the layer of negative ions and the less the opposition of the positive ions in the depletion

region of the n-type material.

- we shall assume that all the minority carriers of the n-type material that find themselves in the depletion region due to their random motion will pass directly into the p-type material. Similar discussion, can be applied to the minority carries. - The majority carriers celeetrone J of the n-type material
 - must overcome the attractive forces of the layer of positive ione intre n-type material and the shield of negative ions in the p-type menterial to migrate into the area beyond the depletion region of the p-type material.
- Similar discussion can be applied to the majority carriers
- in the p-type mentarial. - The resulting flow due to the majority carriers is also

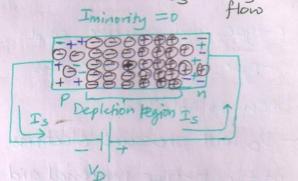
shown in fig.

- The relative magnitude of the flow vectors are such that the flet flow in either direction is zero.
 - This cancellation of rectors has been indicated by crossed lines.
 - In the absence of an applied bias voltage, the net flow of charge in any one direction for a semi wond netor diode 15 zero.

Reverse Bias Condition (VO LOV)

- If external voltage is applied across the p-n junction such as shown in the figure, (Reverse bias wordition) the Is minority carrier

number of uncovered positive ions in the depletion region of the n-type material will increase due to large number of free electron drawn to the positive potential of the applied voltage. For the similar reman,



Reverse-biased p-n junction

the number of uncovered negtive ions will increase in the p-type material.

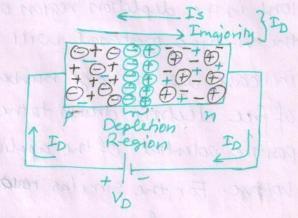
- The net effect is a widening of the depletion region.
 - Effectively reduction in the majority carrier flow to
 - zero as shown in the figure. - It will not change minority carrier flow vectors of the
 - diode.
 - The current that exists under reverse bias conditions is called the reverse saturation current and is represented
 - by Is the Mabien Al - Saturation current is in the range of nano cumpheres to low micro comphers.
 - The term saturation comes from the fact that it reaches its maximum level quickly and does not charge Significantly with increase in reverse biastal potential.

Forward Bins Condition (VD > 0V)

- A forward bias or "on" condition is established as Shown in the figure
- A semiconductor diade is forward biased when the association

p-type and positive and n-type and negative has been established.

- Up will pressure electrons in the n-type material and holes in p-type material to recombine with the ions hear the boundard and



ID = Imajority - Is Forward biased p-h junction

TK= TC+2730

reduce the width of the depletion region as shown in figure. - The resulting minority carrier flow of electrons from p-type material to n-type material and hotes from n-type material to p-type material has not changed in magnitude.

- Reduction in the width of the depletion region has resulted in a heavy majority flow across the junction
- As applied bias increases in magnitude the depletion region will continue to decrease in width untill a flood of electrons can pass through the junction,

resulting in an exponential rise in current &

- It can be demostrated through the use of solid state physics their general characteristics of a semiconductor diode can be defined by the following by for forward - and reverse Is - reverse saturation current K= 11600/m n=1 for Ge ID = Is(eKVD/TK-1 regions " n=2 forsi

Semiconductor Diode V-I Characteristics

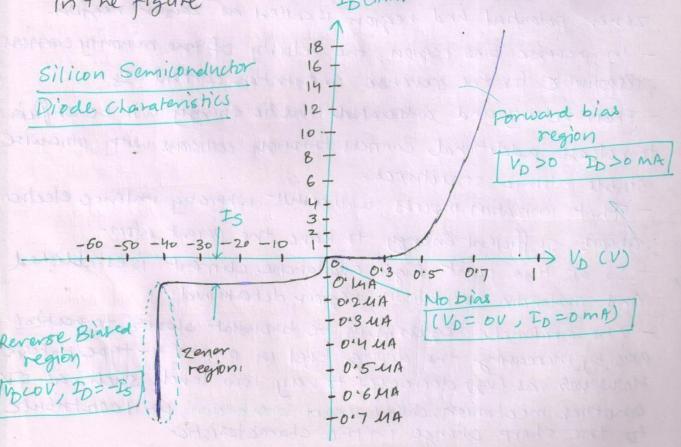
- P-n junction diode formed from junction of n-type and p-type. When it is forward biased, it will pass current when it is reverse biased, current flow is blocked.
- A plot of following equation will descrebe the V-I relationship for each region.

ID = Is (e kvo/Tk - 1)

- For forward biased region, positive values of VD the first term of the equation above will grow very quickly and overpower the effect of the second term.

The result is that for positive values of VD . ID will be positive and grow as the function of y=ex appaing in the figure.

ID CMA)



- At VDZOV ID = Is (et -1) = Is(1+) = 0 mA as appearing in the figure
- For negative values of vp the first term will quickly drop off below Is, resulting Ip = Is which is simply the horizontal line as shown in the figure.
- The break in the characteristics at VD=0V is simply due to the dramatic change in scale from mA to UA.

Zener Region

- As shown in the figure in tens of volts in negative region, there is a point where the application of too negative a voltage will result in a sharp change in the characteristics.
- The current increase at a very rapid rate in a direction opposite to that of the positive voltage region.
- This dramatic charge in characteristics is called the zener potential and region is called as zener region.
- In reverse bias region, the velocity of the minority carriers responsible for the reverse saturation current Is.
- Their velocity and associated kinetic energy will be sufficient to release additional carriers through collisions with otherwise stable atomic structures.
 - That ionization process will result whereby valence electrons absorb sufficient energy to leave the parent atom.
- So at mis point high availante corrent is established and avalante breakdown region determined.
- The avalenche region(visan be brought closer to vertical axis by increasing the doping level in p- and n- type material. However ias (vz) decreases to very low levels, such as-5V, another mechanism, called zener breakdown, will contribute to the sharp change in the characteristic.

- zener breakdown occurs because there is a strong electric field in the region of the junction that can disrupt the bonding forces within the atom and "generate" carriers.
- Although the zener breakdown mechanism is a significant contributor only at lower level of bz, this sharp change in the characteristic at any level is called the zener region and diodes employing this unique portion of the characteristic of a p-n junction are called zenez diodes.

- The maximum reverse bias potential that can be applied before entering the zener region is called the peak inverse voltage (PIV) or peak overese voltage (PRV)

Silicon versus Germanium Iocma) - The disadvantage of Silicon as compared to Germanium, is the higher 20+ forward bias voltage to reach the region of apward swing. V7=0.7(Si) V7=0.3(Ge) IS(SI) = 0.0 MA 5 The potential at which rise occurs V2150/ = 10 ma is commonly referred to as the off-0,10, 50,3 0,20,6 0,1 Is the 1/(40) 203 set, theishold on firing potantial. Value) - Temperature effect V+(Si) 200 > The reverse saturation current Is will just double in magnitude for every 10°C increase in temperature.

- The reverse saturation Current in Silicon flows in order of nano ampheres compared to germanism in which reverse current is in order of micro anphores, because of this the accuracy of non-conduction of the he diddle in reverse bias falls down whereas Si diode retains it property togreater extent i.e. it allows negligible amount of current to flow.
 - Further the Si diade has large reverse breakdown voltage about 70-1000 compared to be which has the reverse breakdown voltage around 500.
 - Typical values of Is for silicon diodes champroseach transamer are much shower man that of Ge.
 - Silicon has better temperature sensitivity than Ge.
 - Cie is used for manufacturing photodiodes over Si.

Advantages of ae.

- Crystal growth possible at lower temperature:
- Substantially higher election and hole mobility indicating potential for higher speed device.

Advantages of Si

- Stable and strong material with same crystal structure as diamond
- Si has a larger bandgap and trus becomes intrinsic at higher temperature. Bardgap enorgy for Si E=1/1er for Ge=0.67ex - Si is less expensive due to greater abudance of element, The major vaw material for Si water fabrication is sand

and there is lots of (8102) available.

Diode Resistance Levels -Diode is a nonlinear device. It has three differentresistance levels described as follows. Incm A 1- DC or Static Resistance -Defined as a point on the Characteristics - The resistance of the diode at the operating point can be found Determining the de mesistance of a Diode at a particular Simply by finding the corresponding operating point. levels of vo and to as shown in fig. RD= Vp Ac or agramic Resistance - Defined by a tangent line at the Q-point. - In general therefore, the cower the Q-point of operation the higher Q-point de operation ac resistance. - An effort should be made to keep the change in voltage and current as small as posible and equidistant to either side of the Q-point. Defining the dynamic or ac resistance Inequation form, a = DVd where - DId afinite change inthe quantity. Determining thear resistance at all-point.

- The den vative of a function at a point is equal to the slope of the tangent line drawn at that point. - weknow that IDZ Is Ce KUD/TK-17 taking the derivative of above equation with respect to the applied bias will result in dup (PD) = d [Is (e KUD/TK-1)] $\frac{dI_0}{dv_0} = \frac{K}{T_0} (I_0 + I_s).$ dro = Lo (because ID >> Is) substituting n=1 for he and si $K = \frac{11600}{9} = 11600$ $7k^2 7c + 273^0 = 25^0 + 273^0$. 1 = 11600 TK = 11600 = 38.93 dPo = 38.93 PD $\frac{dv_0}{d\overline{P}_0} = \frac{0.026}{\overline{I}_0}$ $d = \frac{26mv}{2p}$

